

Electronic Patent Application Fee Transmittal

Application Number:	10829647			
Filing Date:	22-Apr-2004			
Title of Invention:	Methods for assembly and packaging of flip chip configured dice with interposer			
First Named Inventor/Applicant Name:	Teck Kheng Lee			
Filer:	Joseph A. Walkowski/Nancy Johnson			
Attorney Docket Number:	2269-4974.1US (00-0693.01			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Statutory disclaimer	1814	1	130	130
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130